

AMENDMENTS TO THE SPECIFICATION

Please amend the specification as indicated hereafter. It is believed that the following amendments and additions add no new matter to the present application.

AMENDMENTS TO THE CLAIMS

Please amend the claims as indicated hereafter.

Claims:

1. (Previously Presented) A microelectronic device package comprising:
a die attach pad, said pad having a bottom surface;
a plurality of substantially flat electrical connectors formed about a perimeter of said die attach pad, wherein said connectors are configured to couple a device to a substrate;
a coupling of a plurality of wires from said device package to one of said connectors; and
an encapsulant surrounding a portion of said electrical connectors and a portion of said die attach pad, wherein said bottom surface of said die attach pad is substantially free of encapsulant.

2. (Previously Presented) The microelectronic device package according to claim 1, wherein said connectors and said pad are formed from a leadframe.

3-20. (Cancelled)

21. (Previously Presented) The microelectronic device package according to claim 1, wherein said pad is not offset from said connectors.

22. (Previously Presented) The microelectronic device package according to claim 1, wherein said pad is configured to mechanically bond to a device.

23. (Previously Presented) The microelectronic device package according to claim 1, wherein said wire is formed of gold wire having a diameter of approximately 25 microns.

24. (Previously Presented) The microelectronic device package according to claim 1, wherein bottom surface of said connectors is substantially free of encapsulant.

25. (Previously Presented) The microelectronic device package according to claim 1, wherein said encapsulant is epoxy resin.

El 26. (Previously Presented) The microelectronic device package according to claim 1, wherein the conductive path length through said connector is the thickness of said connector.

27. (Previously Presented) The microelectronic device package according to claim 2, wherein said connectors and said die pad feature undercut regions to assist in attachment of said encapsulant.

28. (Cancelled)

29. (Previously Presented) The microelectronic device package according to claim 1, wherein portions of a device are electronically coupled to said die pad.

30. (Cancelled)

31. (Previously Presented) The microelectronic device package according to claim 1, wherein said connectors are formed from a metal frame.

32. (Previously Presented) The microelectronic device package according to claim 1, wherein said pad is formed from a metal frame.

33. (Currently Amended) The microelectronic device package according to claim 31 or 32, wherein said frame is formed of copper.

34. (Currently Amended) The microelectronic device package according to claim 31 or 32, wherein said frame is formed of a copper metal sheet having a thickness of approximately 200 microns.

35. (Previously Presented) The microelectronic device package according to claim 31, wherein said frame is coated with about 10 micro inches of palladium.

36. (Previously Presented) The microelectronic device package according to claim 22, wherein said device is bonded to said pad using conductive epoxy.

37-53. (Cancelled)
